

Product/process change notification

PCN N° 2021-118-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Introduction of an additional wafer production site at Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia for EC4_650V and of IGBT MPT in 300 mm at Infineon Technologies Dresden GmbH, Dresden, Germany for CIPOS™ Mini Products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-03-23
- Infineon aligns with the widely recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Infineon Technologies AG

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Chairman of the Supervisory Board: Dr. Wolfgang Eder

Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492



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Products affected

Please refer to attached affected product list 1_cip21118_a

▶ Detailed change information

Subject

Introduction of an additional FE wafer site production and implementation of 300mm wafer diameter

Reason

Capacity extension and implementation of a 2nd source

Description

Wafer production and test site EC4 650V

<u>Old</u>

- Infineon Technologies Austria AG, Villach
- Infineon Technologies (Kulim) Sdn. Bhd., Kulim

New

or Infineon Technologies Austria AG, Villach

Wafer diameter / production, test site IGBT MPT

- 200 mm / Infineon Technologies Austria AG, Villach
- 300 mm / Infineon
 Technologies Austria AG,
 Dresden
 or
 200mm / Infineon
 Technologies Austria AG,
 Villach

Product identification

Internal traceability assured via lot code and development code. External traceability assured via Product Bar Code Label / Lot Code

Impact of change

No Impact on parameters and reliability as proven via product qualification. Processes are optimized to meet identical product performance according to already applied Infineon specifications.

Attachments

Affected product list 1_ cip21118_a

Qualification report 2_ cip21118_a



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Time schedule

Final qualification report Available (refer to attachment 2_cip21118_a)

First samples available

yes

Intended start of delivery

2022-05-15 or earlier on specific customer request

If you have any questions, please do not hesitate to contact your local sales office.



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Sales name	SP number	OPN	Package
IFCM10P60GD	SP001615606	IFCM10P60GDXKMA1	DIP 36x21D
IFCM10S60GD	SP001615598	IFCM10S60GDXKMA1	DIP 36x21D
IFCM15P60GD	SP001614382	IFCM15P60GDXKMA1	DIP 36x21D
IFCM15S60GD	SP001504638	IFCM15S60GDXKMA1	DIP 36x21D
IFCM15S60GS	SP001678818	IFCM15S60GSXKMA1	DIP 36x21D
IFCM20T65GD	SP001333972	IFCM20T65GDXKMA1	DIP 36x21D
IFCM20U65GD	SP001423502	IFCM20U65GDXKMA1	DIP 36x21D
IFCM30T65GD	SP001423504	IFCM30T65GDXKMA1	DIP 36x21D
IFCM30U65GD	SP001423506	IFCM30U65GDXKMA1	DIP 36x21D
IM564-X6D	SP005408854	IM564X6DXKMA1	DIP 36x21D